

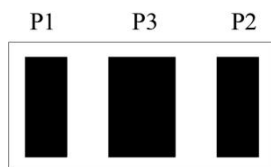
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

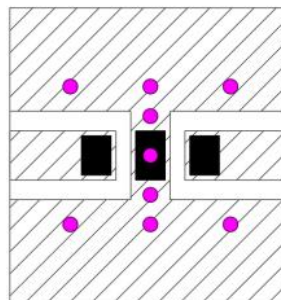
NO.	Parameter	SPC
1	Frequency range	3300-3800 MHz
2	Insertion Loss	2.6dB max. at +25°C
3	Attenuation	30 dB min. @ 1400-2000 MHz 25 dB min. @ 2400-2700 MHz 30 dB min. @ 4900-5850 MHz
4	Return Loss (In BW)	10.0 min. dB
5	Port Impedance	50Ω
6	Power	1.0W max.
7	Operation Temperature Range	-40°C ~ +85°C

Construction



PIN	Connection
1	Input port
2	Output port
3	GND

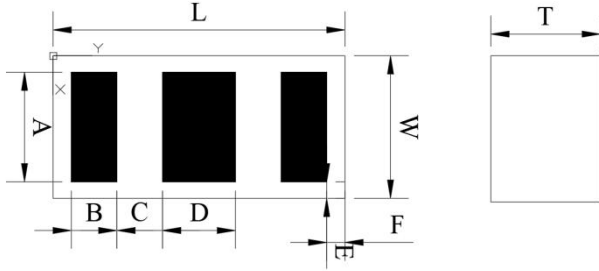
Mounting Considerations



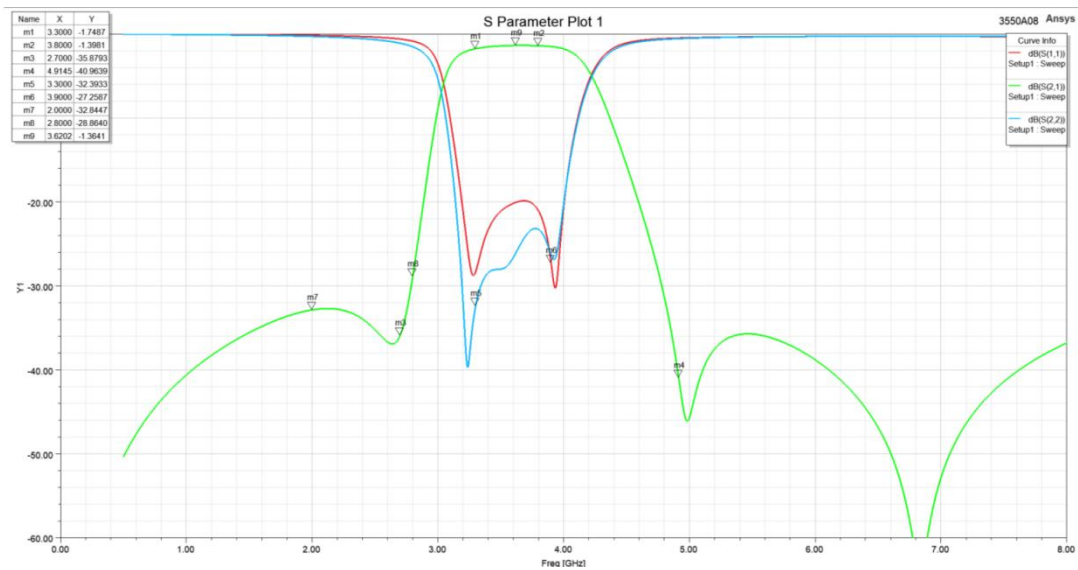
- Land
- ▨ Solder
- Through-hole

Unit: mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

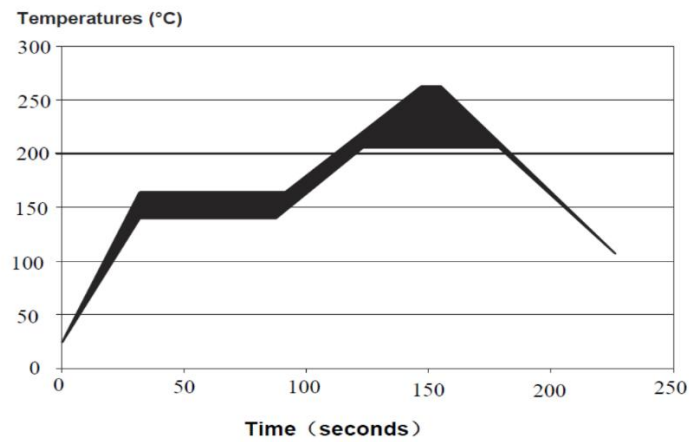
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.6 ± 0.10
	B	0.25 ± 0.10
	C	0.25 ± 0.10
	D	0.40 ± 0.10
	E	0.10 ± 0.10
F	0.10 ± 0.10	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.